nanoHUB: Use of External Resources by External Researchers

Research Article

Analysis of CNT Bundle and Its Comparison with Copper Interconnect for CMOS and CNFET Drivers

Abdul Kadir Kureshi and Mohd. Hasan Department of Electronics Engineering, Aligarh Muslim University, Aligarh 202002, India Correspondence should be addressed to Abdul Kadir Kureshi, akkureshi@rediffmail.com Received 18 April 2009; Accepted 26 August 2009 Recommended by Donald Bansleben In nanoscale regime as the CMOS process technolo major hurdle for onchip communication due to hi evaluation of mixed CNT bundle interconnects and in anoscale-integrated circuits. The performance of manisation (CNFET) as a driver and compencets and in anoscale-integrated circuits. The performance of manisation (CNFET) as a driver and compared with HSPICE simulations are carried out at operating f with CNFET as the driver can potentially provide c 23 nm process technology. Similarly, the CNFET drivense disaster rate asserter rate a

The analysis of our external literature citations revealed some examples where external theory-driven researchers utilized a nanoHUB tool that has been contributed to nanoHUB from outside of the NCN. For example the authors Kureshi and Hasan working at a university in India published their study CNT bundles as possible copper replacement interconnects in the "Journal of Nanomaterials" in April 2009. In their work they utilized the tool "Carbon Nanotubes Interconnect Analyzer (CNIA)" for over 1,600 simulations in the year 2009 alone. CNIA was contributed by Tanachutiwat and Wang of the University of Albany. We cannot see any relationship between the two research groups and NCN other than the contributed, efficiently served, and utilized tool CNIA. The same CNIA tool has previously also been cited in a Master's thesis at the University of Cincinnati in 27 the year 2005. The concept of community contributions coming from outside the NCN and being useful for an unrelated research group is becoming reality.